

# PATENT ASSIGNMENT

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<b>SUBMISSION TYPE:</b>	NEW ASSIGNMENT
<b>NATURE OF CONVEYANCE:</b>	ASSIGNMENT
<b>CONVEYING PARTY DATA</b>	
<b>Name</b>	<b>Execution Date</b>
Jason Dai	07/16/2004
<b>RECEIVING PARTY DATA</b>	
<b>Name:</b>	Intel Corporation
<b>Street Address:</b>	2200 Mission College Blvd.
<b>City:</b>	Santa Clara
<b>State/Country:</b>	CALIFORNIA
<b>Postal Code:</b>	95052
<b>PROPERTY NUMBERS Total: 1</b>	
<b>Property Type</b>	<b>Number</b>
Application Number:	10835083
<b>CORRESPONDENCE DATA</b>	
<b>Fax Number:</b>	(203)972-7627
<i>Correspondence will be sent via US Mail when the fax attempt is unsuccessful.</i>	
<b>Phone:</b>	203-972-0006
<b>Email:</b>	levin@bmtpatent.com
<b>Correspondent Name:</b>	Buckley, Maschoff & Talwalkar LLC
<b>Address Line 1:</b>	Five Elm Street
<b>Address Line 4:</b>	New Canaan, CONNECTICUT 06840
<b>NAME OF SUBMITTER:</b>	Nathaniel Levin
<b>Total Attachments: 2</b> source=I06.242 Scanned Assign for Jason Dai#page1.tif source=I06.242 Scanned Assign for Jason Dai#page2.tif	

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**PATENT**  
**REEL: 014869 FRAME: 0561**

## ASSIGNMENT OF RIGHTS, TITLE AND INTEREST IN INVENTION

This is an Assignment of the following rights, title and interest: *(check all that apply)*

- ☒ United States of America rights, title and interest in the invention
- ☒ Foreign rights, title and interest in the invention
- ☒ United States Patent Application No.: 10/835,083
- Date of Execution:                      Date of Filing: April 29, 2004
- ☐ United States Provisional Patent Application Serial No.
- ☐ United States Patent No(s).
- ☐ International (PCT) Patent Application Serial No.
- ☐ Other (*specify*):

### TITLE OF THE INVENTION:

**DEBUGGING TOOL FOR DEBUGGING MULTI-THREADED  
PROGRAMS**

### Inventor (*assignor*)

Name	Address
Jason Dai	Room 309, Block 2, Ren Le Xin Cun, Songjiang District, Shanghai, PR China 201600

### Assignee

Name	Address
Intel Corporation	2200 Mission College Blvd., Santa Clara, CA USA 95052

Whereas, I, the above-identified Inventor, have invented certain new and useful improvements in the Invention identified above and described in the above-identified patent application(s) and/or patent(s) (hereinafter referred to as "Invention");

And, whereas I desire to assign my above-identified rights, title and interest in the Invention to **Intel Corporation**, 2200 Mission College Blvd., Santa Clara, CA USA 95052;

Now, this indenture witnesseth, that for good and valuable consideration, the receipt whereof is hereby acknowledged;

I hereby assign, sell and transfer my above-identified rights, title and interest in said Invention, said application(s) as identified above, including any divisions, continuations, and continuations-in-part thereof, and in and to any and all Letters Patent of the United States, and countries foreign thereto, which may be granted or have granted for said Invention, and in and to any and all reissues and reexaminations thereof, and in and to any and all priority rights, Convention rights, and other benefits accruing or to accrue to me with respect to the filing of applications for patents or securing of patents in the United States and countries foreign thereto, unto said Assignee;

And I hereby authorize and request the Commissioner of Patents and Trademarks to issue any United States Letters Patent which may issue for said Invention to said Assignee, as assignee of the whole right, title and interest thereto;

And I further agree to sign and execute all necessary and lawful future documents, including applications for foreign patents, for filing divisions, continuations and continuations-in-part of said application for patent, and/or, for obtaining any reissue or reissues of any Letters Patent which may be granted for my aforesaid Invention, as the Assignee or its Designee(s) may from time to time require and prepare at its own expense.

Inventor's Signature

July 16  
Date

Jason Dai  
Jason Dai